

#### Data Sheet

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# Dual LDO with Low Noise, Low I<sub>Q</sub>, and High PSRR

intercil

ISL9011A is a high performance dual LDO capable of sourcing 150mA current from Channel 1 and 300mA from Channel 2. The device has a low standby current and high-PSRR and is stable with output capacitance of  $1\mu$ F to  $10\mu$ F with ESR of up to  $200m\Omega$ .

A reference bypass pin allows an external capacitor for adjusting a noise filter for low noise and high PSRR applications.

The quiescent current is typically only  $45\mu$ A with both LDO's enabled and active. Separate enable pins control each individual LDO output. When both enable pins are low, the device is in shutdown, typically drawing less than  $0.1\mu$ A.

Several combinations of voltage outputs are standard. Others are available on request. Output voltage options for each LDO range from 1.2V to 3.6V.

## Pinout

ISL9011A (10 LD 3x3 DFN) TOP VIEW



#### Features

- Integrates two high performance LDOs
  - VO1 150mA output
  - VO2 300mA output
- Excellent transient response to large current steps
- Excellent load regulation: <1% voltage change across full range of load current
- High PSRR: 70dB @ 1kHz
- Wide input voltage capability: 2.3V to 6.5V
- Extremely low quiescent current: 45µA (both LDOs active)
- Low dropout voltage: typically 120mV @ 150mA
- Low output noise: typically 30µV<sub>RMS</sub> @ 100µA (1.5V)
- Stable with 1µF to 10µF ceramic capacitors
- · Separate enable pins for each LDO
- · Soft-start to limit input current surge during enable
- · Current limit and overheat protection
- ±1.8% accuracy over all operating conditions
- Tiny 10 Ld 3mmx3mm DFN package
- -40°C to +85°C operating temperature range
- Pin compatible with Micrel MIC2211
- · Pb-free plus anneal available (RoHS compliant)

## Applications

- · PDAs, Cell Phones and Smart Phones
- · Portable Instruments, MP3 Players
- Handheld Devices including Medical Handhelds

## **Ordering Information**

PART NUMBER (Notes 1, 2, 3)	PART MARKING	VO1 VOLTAGE (V)	VO2 VOLTAGE (V)	TEMP RANGE (°C)	PACKAGE (Pb-free)	PKG. DWG. #
ISL9011AIRNNZ	DGPA	3.3	3.3	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRNJZ	DGNA	3.3	2.8	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRNFZ	DGMA	3.3	2.5	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRNCZ	DGLA	3.3	1.8	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRMNZ	DGKA	3.0	3.3	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRMMZ	DGJA	3.0	3.0	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRMGZ	DGHA	3.0	2.7	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRLLZ	DGGA	2.9	2.9	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRKNZ	DGEA	2.85	3.3	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRKKZ	DGDA	2.85	2.85	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRKJZ	DGCA	2.85	2.8	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRKFZ	DGBA	2.85	2.5	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRKPZ	DGFA	2.85	1.85	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRKCZ	DFYA	2.85	1.8	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRJNZ	DFVA	2.8	3.3	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRJMZ	DFTA	2.8	3.0	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRJRZ	DWFA	2.8	2.6	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRJCZ	DFSA	2.8	1.8	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRJBZ	DFRA	2.8	1.5	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRGPZ	DFPA	2.7	1.85	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRGCZ	DFNA	2.7	1.8	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRFJZ	DFMA	2.5	2.8	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRFDZ	DFLA	2.5	2.0	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRFCZ	DFKA	2.5	1.8	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRPLZ	DGRA	1.85	2.9	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRPPZ	DGSA	1.85	1.85	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRCJZ	DFJA	1.8	2.8	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRCCZ	DFHA	1.8	1.8	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRBLZ	DFGA	1.5	2.9	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRBJZ	DFFA	1.5	2.8	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRBCZ	DFEA	1.5	1.8	-40 to +85	10 Ld 3x3 DFN	L10.3x3C
ISL9011AIRBBZ	DFDA	1.5	1.5	-40 to +85	10 Ld 3x3 DFN	L10.3x3C

NOTES:

1. Add -T to part number for tape and reel.

2. For availability and lead time of devices with voltage combinations not listed in the table, contact Intersil Marketing.

3. Intersil Pb-free plus anneal products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

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#### **Absolute Maximum Ratings**

Supply Voltage (VIN)+	7.1V
All Other Pins $\dots \dots \dots$	.3)V

#### **Recommended Operating Conditions**

Ambient Temperature Range (T <sub>A</sub> )	40°C to +85°C
Supply Voltage (VIN)	

#### **Thermal Information**

Thermal Resistance (Notes 4, 5)	θ <sub>JA</sub> (°C/W)	θ <sub>JC</sub> (°C/W)
3x3 DFN Package	50	10
Junction Temperature Range		°C to +125°C
Operating Temperature Range		0°C to +85°C
Storage Temperature Range	65°	°C to +150°C
Maximum Lead Temperature (Soldering 1	0s)	+300°C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTES:

- 4. θ<sub>JA</sub> is measured in free air with the component mounted on a high effective thermal conductivity test board with "direct attach" features. See Tech Brief TB379.
- 5.  $\theta_{JC}$ , "case temperature" location is at the center of the exposed metal pad on the package underside. See Tech Brief TB379.

Electrical Specifications	Unless otherwise noted, all parameters are guaranteed over the operational supply voltage and temperature
	range of the device as follows: $T_A = -40^{\circ}C$ to $+85^{\circ}C$ ; $V_{IN} = (V_O+1.0V)$ to 6.5V with a minimum $V_{IN}$ of 2.3V;
	$C_{IN} = 1\mu F; C_O = 1\mu F; C_{BYP} = 0.01\mu F$

PARAMETER	PARAMETER SYMBOL TEST CONDITIONS		MIN	TYP	MAX	UNITS
DC CHARACTERISTICS			!	!		!
Supply Voltage	V <sub>IN</sub>		2.3		6.5	V
Ground Current		Quiescent condition: $I_{O1} = 0\mu A$ ; $I_{O2} = 0\mu A$				
	I <sub>DD1</sub>	One LDO active		25	40	μA
	I <sub>DD2</sub>	Both LDO active		45	60	μA
Shutdown Current	IDDS	@ +25°C		0.1	1.0	μA
UVLO Threshold	V <sub>UV+</sub>		1.9	2.1	2.3	V
	V <sub>UV-</sub>		1.6	1.8	2.0	V
Regulation Voltage Accuracy		Variation from nominal voltage output, $V_{IN} = V_O + 0.5$ to 5.5V, T <sub>J</sub> = -40°C to +125°C	-1.8		+1.8	%
Line Regulation		$V_{IN}$ = (V <sub>OUT</sub> +1.0V relative to highest output voltage) to 5.5V	-0.2	0	0.2	%/V
Load Regulation		I <sub>OUT</sub> = 100µA to 150mA (VO1 and VO2)		0.1	0.7	%
		I <sub>OUT</sub> = 100μA to 300mA (VO2)			1.0	%
Maximum Output Current	I <sub>MAX</sub>	VO1: Continuous	150			mA
		VO2: Continuous	300			mA
Internal Current Limit	I <sub>LIM</sub>		350	475	600	mA
Dropout Voltage (Note 6)	V <sub>DO1</sub>	I <sub>O</sub> = 150mA; V <sub>O</sub> > 2.1V (VO1)		125	200	mV
	V <sub>DO2</sub>	I <sub>O</sub> = 300mA; V <sub>O</sub> < 2.5V (VO2)		300	500	mV
	V <sub>DO3</sub>	$I_O$ = 300mA; 2.5V $\leq$ V_O $\leq$ 2.8V (VO2)		250	400	mV
	V <sub>DO4</sub>	I <sub>O</sub> = 300mA; V <sub>O</sub> > 2.8V (VO2)		200	325	mV
Thermal Shutdown Temperature	T <sub>SD+</sub>			145		°C
	T <sub>SD-</sub>			110		°C
AC CHARACTERISTICS			1			
Ripple Rejection		I <sub>O</sub> = 10mA, V <sub>IN</sub> = 2.8V(min), V <sub>O</sub> = 1.8V, C <sub>BYP</sub> = 0.1μF				
		@ 1kHz		70		dB
		@ 10kHz		55		dB
		@ 100kHz		40		dB
Output Noise Voltage		I <sub>O</sub> = 100μA, V <sub>O</sub> = 1.5V, T <sub>A</sub> = +25°C, C <sub>BYP</sub> = 0.1μF BW = 10Hz to 100kHz		30		μV <sub>RMS</sub>

# **Electrical Specifications** Unless otherwise noted, all parameters are guaranteed over the operational supply voltage and temperature range of the device as follows: $T_A = -40^{\circ}C$ to $+85^{\circ}C$ ; $V_{IN} = (V_O+1.0V)$ to 6.5V with a minimum $V_{IN}$ of 2.3V; $C_{IN} = 1\mu$ F; $C_O = 1\mu$ F; $C_{BYP} = 0.01\mu$ F (**Continued**)

PARAMETER	PARAMETER SYMBOL TEST CONDITIONS		MIN	TYP	MAX	UNITS		
DEVICE START-UP CHARACT	DEVICE START-UP CHARACTERISTICS							
Device Enable TIme	vice Enable TIme t <sub>EN</sub> Time from assertion of the ENx pin to when the output voltage reaches 95% of the VO(nom)			250	500	μs		
LDO Soft-Start Ramp Rate	tSSR	Slope of linear portion of LDO output voltage ramp during start- up		30	60	µs/V		
EN1, EN2 PIN CHARACTERIS	EN1, EN2 PIN CHARACTERISTICS							
Input Low Voltage	V <sub>IL</sub>		-0.3		0.5	V		
Input High Voltage	VIH		1.4		V <sub>IN</sub> +0.3	V		
Input Leakage Current	I <sub>IL</sub> , I <sub>IH</sub>				0.1	μA		
Pin Capacitance	C <sub>PIN</sub>	Informative		5		pF		

NOTE:

6. VOx = 0.98 \* VOx(NOM); Valid for VOx greater than 1.85V.













FIGURE 2. OUTPUT VOLTAGE CHANGE vs LOAD CURRENT







## Typical Performance Curves (Continued)

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## Typical Performance Curves (Continued)

FIGURE 13. LINE TRANSIENT RESPONSE, 3.3V OUTPUT



FIGURE 14. LINE TRANSIENT RESPONSE, 2.8V OUTPUT



FIGURE 15. LOAD TRANSIENT RESPONSE





# **Pin Descriptions**

PIN #	PIN NAME	ТҮРЕ	DESCRIPTION
1	VIN	Analog I/O	Supply Voltage/LDO Input: Connect a 1µF capacitor to GND.
2	EN1	Low Voltage Compatible CMOS Input	LDO-1 Enable.
3	EN2	Low Voltage Compatible CMOS Input	LDO-2 Enable.
4	CBYP	Analog I/O	Reference Bypass Capacitor Pin: Optionally connect capacitor of value $0.01\mu$ F to $1\mu$ F between this pin and GND to tune in the desired noise and PSRR performance.
5, 7, 8	NC	NC	No Connection
6	GND	Ground	GND is the connection to system ground. Connect to PCB Ground plane.
9	VO2	Analog I/O	LDO-2 Output: Connect capacitor of value $1\mu$ F to $10\mu$ F to GND ( $1\mu$ F recommended).
10	VO1	Analog I/O	LDO-1 Output: Connect capacitor of value $1\mu$ F to $10\mu$ F to GND ( $1\mu$ F recommended).

# **Typical Application**



C1, C3, C4: 1µF X5R ceramic capacitor C2: 0.1µF X5R ceramic capacitor

## Block Diagram



# **Functional Description**

The ISL9011A contains all circuitry required to implement two high performance LDOs. High performance is achieved through a circuit that delivers fast transient response to varying load conditions. In a quiescent condition, the ISL9011A adjusts its biasing to achieve the lowest standby current consumption.

The device also integrates current limit protection, smart thermal shutdown protection, staged turn-on and soft-start. Smart Thermal shutdown protects the device against overheating. Staged turn-on and soft-start minimize start-up input current surges without causing excessive device turnon time.

#### **Power Control**

The ISL9011A has two separate enable pins (EN1 and EN2) to individually control power to each of the LDO outputs. When both EN1 and EN2 are low, the device is in shutdown

mode. During this condition, all on-chip circuits are off, and the device draws minimum current, typically less than  $0.1\mu$ A. When one or both of the enable pins are asserted, the device first polls the output of the UVLO detector to ensure that VIN voltage is at least about 2.1V. Once verified, the device initiates a start-up sequence. During the start-up sequence, trim settings are first read and latched. Then, sequentially, the bandgap, reference voltage and current generation circuitry power-up. Once the references are stable, a fast-start circuit quickly charges the external reference bypass capacitor (connected to the CBYP pin) to the proper operating voltage. After the bypass capacitor has been charged, the LDO's power-up.

If EN1 is brought high, and EN2 goes high before the VO1 output stabilizes, the ISL9011A delays the VO2 turn-on until the VO1 output reaches its target level.

If EN2 is brought high, and EN1 goes high before VO2 starts its output ramp, then VO1 turns on first and the ISL9011A

delays the VO2 turn-on until the VO1 output reaches its target level.

If EN2 is brought high, and EN1 goes high after VO2 starts its output ramp, then the ISL9011A immediately starts to ramp up the VO1 output.

If both EN1 and EN2 are brought high at the same time, the VO1 output has priority, and is always powered up first.

During operation, whenever the VIN voltage drops below about 1.8V, the ISL9011A immediately disables both LDO outputs. When VIN rises back above 2.1V, the device reinitiates its start-up sequence and LDO operation will resume automatically.

#### **Reference Generation**

The reference generation circuitry includes a trimmed bandgap, a trimmed voltage reference divider, a trimmed current reference generator, and an RC noise filter. The filter includes the external capacitor connected to the CBYP pin. A 0.01 $\mu$ F capacitor connected CBYP implements a 100Hz lowpass filter, and is recommended for most high performance applications. For the lowest noise application, a 0.1 $\mu$ F or greater CBYP capacitor should be used. This filters the reference noise to below the 10Hz to 1kHz frequency band, which is crucial in many noise-sensitive applications.

The bandgap generates a zero temperature coefficient (TC) voltage for the reference divider. The reference divider provides the regulation reference and other voltage references required for current generation and over-temperature detection.

The current generator outputs references required for adaptive biasing as well as references for LDO output current limit and thermal shutdown determination.

## LDO Regulation and Programmable Output Divider

The LDO Regulator is implemented with a high-gain operational amplifier driving a PMOS pass transistor. The design of the ISL9011A provides a regulator that has low quiescent current, fast transient response, and overall stability across all operating and load current conditions. LDO stability is guaranteed for a  $1\mu$ F to  $10\mu$ F output capacitor that has a tolerance better than 20% and ESR less than  $200m\Omega$ . The design is performance-optimized for a  $1\mu$ F capacitor. Unless limited by the application, use of an output capacitor value above  $4.7\mu$ F is not recommended as LDO performance improvement is minimal.

Soft-start circuitry integrated into each LDO limits the initial ramp-up rate to about  $30\mu$ s/V to minimize current surge. The ISL9011A provides short-circuit protection by limiting the output current to about 475mA.

Each LDO uses an independently trimmed 1V reference. An internal resistor divider drops the LDO output voltage down to 1V. This is compared to the 1V reference for regulation. The resistor division ratio is programmed in the factory.

## **Overheat Detection**

The bandgap outputs a proportional-to-temperature current that is indicative of the temperature of the silicon. This current is compared with references to determine if the device is in danger of damage due to overheating. When the die temperature reaches about +145°C, one or both of the LDO's momentarily shut down until the die cools sufficiently. In the overheat condition, only the LDO sourcing more than 50mA will be shut off. This does not affect the operation of the other LDO. If both LDOs source more than 50mA and an overheat condition occurs, both LDO outputs are disabled. Once the die temperature falls back below about +110°C, the disabled LDO(s) are re-enabled and soft-start automatically takes place.

## Dual Flat No-Lead Plastic Package (DFN)



#### L10.3x3C

10 LEAD DUAL FLAT NO-LEAD PLASTIC PACKAGE

	ſ			
SYMBOL	MIN NOMINAL MAX			NOTES
А	0.85	0.90	0.95	-
A1	-	-	0.05	-
A3		0.20 REF		-
b	0.20 0.25 0.3			5, 8
D		-		
D2	2.33	2.38	2.43	7, 8
E		3.00 BSC		-
E2	1.59	1.64	1.69	7, 8
е	0.50 BSC			-
k	0.20	-	-	-
L	0.35	0.40	0.45	8
N	10			2
Nd	5			3
-	Rev. 1 4/06			

NOTES:

- 1. Dimensioning and tolerancing conform to ASME Y14.5-1994.
- 2. N is the number of terminals.
- 3. Nd refers to the number of terminals on D.
- 4. All dimensions are in millimeters. Angles are in degrees.
- 5. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
- 6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
- 7. Dimensions D2 and E2 are for the exposed pads which provide improved electrical and thermal performance.
- 8. Nominal dimensions are provided to assist with PCB Land Pattern Design efforts, see Intersil Technical Brief TB389.
- 9. COMPLIANT TO JEDEC MO-229-WEED-3 except for dimensions E2 & D2.

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